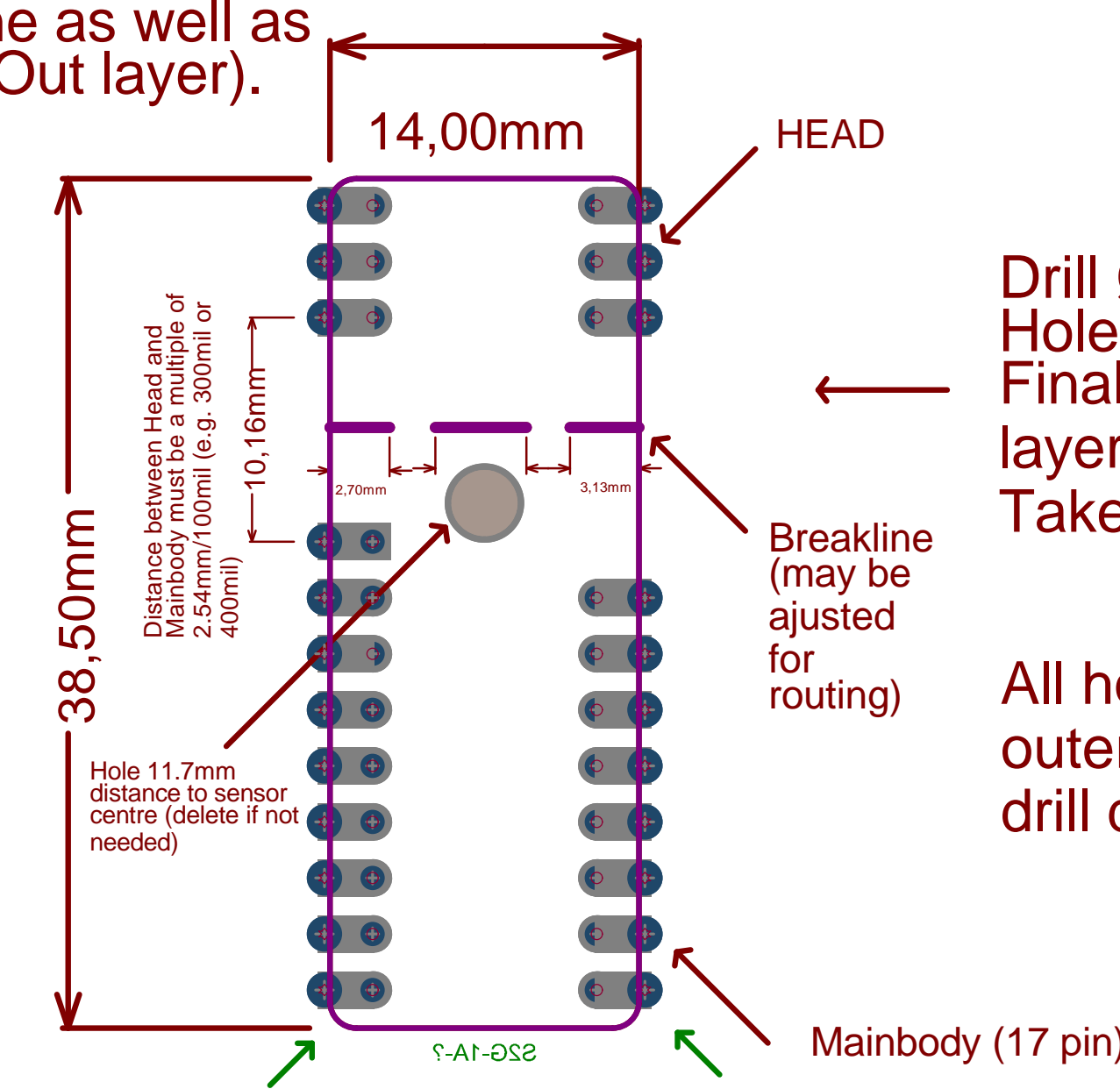


Drill Legend

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
□	1	3,000mm (118,11mil)	PTH	Round	L1_Top - L2_Bot	Via	Rounded	v360h300m360			
○	23	1,100mm (43,31mil)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
☆	23	1,600mm (62,99mil)	PTH	Round	L1_Top - L2_Bot	Pad	Rectangle	(Mixed)			
	47 Total										

Information on Drilling

Lines in Drill Guide indicate board outline as well as board cutouts (find same lines in Keep-Out layer).



Drill Ø 0.5 mm.
Holes are final dimension. Distribute cut-outs as needed in your design. Final dimension of inner board cut-out are lines (as in Keep-Out layer).
Take care of copper between cut-outs.

All holes on long sides plated;
outer holes (greater ones) designed as 'Castellated Holes', compare drill drawing legend.

Please assemble Pins for Socket S2 (9 & 8 Pins) with Male/2.54mm pitch from the bottom, if marked as "assembled" in BOM

MATERIAL SPECIFICATION			
SINGLE SIDED	DOUBLESIDED	MULTILAYER	
MATERIAL	FR4	TG130	TC200
RoHS conform		YES	NO
IPC-A-600H	CLASS1	CLASS2	CLASS3
PCB THICKNESS mm			1.68
COPPER THICKNESS AFTER PLATING um	9	18	35
SURFACE	HAL leadfree		
	Ni/Au		
	chem-Sn		
THROUGH PLATED BOARD		YES	NO
SOLDER MASK	RED	TOP	YES
	RED	BOT	YES
SILK-SCREEN	WHITE	TOP	YES
	WHITE	BOT	YES
TEST		ELECTRICAL	YES
		AOI	YES

Layer Stack Up Detail for: Project Title [No Variations]

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Overlay	(.GTO)					
Top Solder	(.GTS)					
L1_Top	(.GTL)	0.035mm	1.57mm	FR-4	4.7	Core
L2_Bot	(.GBL)	0.035mm				
Bottom Solder	(.GBS)					
Bottom Overlay	(.GBO)					

TECHNOLOGY

TRACK WIDTH: 0.30mm
CLEARANCE: 0.20mm
ANNULAR RING: 0.3mm
HOLE SIZE: 0.300mm

ALL DIMENSIONS AND HOLES ARE FINAL
THE THICKNESS OF THE INSULATING
LAYERS IS OBLIGATORY

CREATED BY

Infineon Technologies AG
Address
© Infineon Technologies AG 2020. All Rights Reserved.

Contact Name Name
Contact Phone ':PRJ_Responsible_Phone'
Contact Email ':PRJ_Responsible_Mail'

<p>Infineon Technologies AG Team Am Campeon 1-12 85579 NEUBIBERG - GERMANY</p>	ENGINEER:	TITLE:		
	PCB DESIGNER:	Project Title		
	DATE:	04.03.2020	PART NO.:	REL: Name
	SVN REVISION:	Not In VersionControl	FILE NAME:	SCALE: 1:1
		APRV: Name	REV: V1.0	
		PCB_S2G.PcbDoc		